INTEGRATED CIRCUITS

DATA SHEET

74LV125Quad buffer/line driver (3-State)

Product specification Supersedes data of 1997 Feb 03 IC24 Data Handbook







Philips Semiconductors Product specification

Quad buffer/line driver (3-State)

74LV125

FEATURES

- Wide operating voltage: 1.0 to 5.5 V
- Optimized for Low Voltage applications: 1.0 to 3.6 V
- ullet Accepts TTL input levels between V_{CC} = 2.7 V and V_{CC} = 3.6 V
- Typical V_{OLP} (output ground bounce) < 0.8 V at V_{CC} = 3.3 V, $T_{amb} = 25$ °C.
- Typical V_{OHV} (output V_{OH} undershoot) > 2 V at V_{CC} = 3.3 V, $T_{amb} = 25^{\circ}C.$
- Output capability: bus driver
- I_{CC} category: MSI

DESCRIPTION

The 74LV125 is a low-voltage Si-gate CMOS device and is pin and function compatible with 74HC/HCT125.

The 74LV125 consists of four non-inverting buffers/line drivers with 3-state outputs. The 3-state outputs (nY) are controlled by the output enable input (nOE). A HIGH at nOE causes the outputs to assume a high impedance OFF-state.

QUICK REFERENCE DATA

GND = 0 V; $T_{amb} = 25^{\circ}C$; $t_r = t_f \le 2.5 \text{ ns}$

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t _{PHL} /t _{PLH}	Propagation delay nA to nY	$C_L = 15 \text{ pF};$ $V_{CC} = 3.3 \text{ V}$	9	ns
C _I	Input capacitance		3.5	pF
C _{PD}	Power dissipation capacitance per buffer	$V_{CC} = 3.3 \text{ V};$ $V_I = \text{GND to } V_{CC}^{-1}$	22	pF

NOTE:

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μW) P_D is asset to determine the dynamic power dissipation (P_D in $\mu\nu$) $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum_{j=1}^{n} (C_L \times V_{CC}^2 \times f_j)$ where: f_i = input frequency in MHz; C_L = output load capacitance in pF; f_0 = output frequency in MHz; V_{CC} = supply voltage in V;

 $\sum (C_L \times V_{CC}^2 \times f_0) = \text{sum of the outputs.}$

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	PKG. DWG. #
14-Pin Plastic DIL	-40°C to +125°C	74LV125 N	74LV125 N	SOT27-1
14-Pin Plastic SO	-40°C to +125°C	74LV125 D	74LV125 D	SOT108-1
14-Pin Plastic SSOP Type II	-40°C to +125°C	74LV125 DB	74LV125 DB	SOT337-1
14-Pin Plastic TSSOP Type I	-40°C to +125°C	74LV125 PW	74LV125PW DH	SOT402-1

PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1, 4, 10, 13	1 0E – 4 0E	Data enable inputs (active LOW)
2, 5, 9, 12	1A – 4A	Data inputs
3, 6, 8, 11	1Y – 4Y	Data Outputs
7	GND	Ground (0 V)
14	V _{CC}	Positive supply voltage

FUNCTION TABLE

INP	INPUTS							
nOE	nA	nY						
L	L	L						
L	Н	Н						
Н	X	Z						

NOTES:

H = HIGH voltage level

L = LOW voltage level

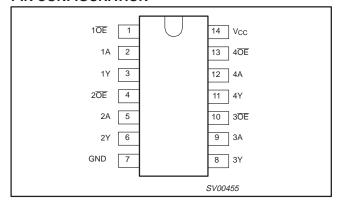
Z = high impedance OFF-state

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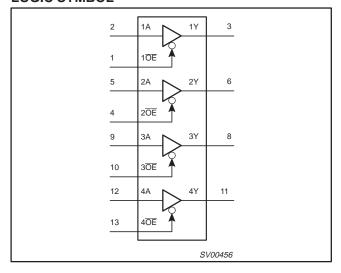
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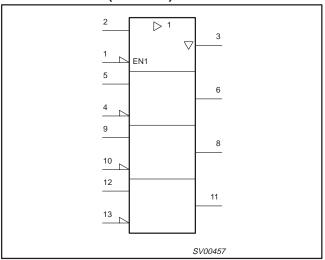
PIN CONFIGURATION



LOGIC SYMBOL



LOGIC SYMBOL (IEEE/IEC)



RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
V _{CC}	DC supply voltage	See Note 1	1.0	3.3	5.5	V
V _I	Input voltage		0	-	V _{CC}	V
Vo	Output voltage		0	_	V _{CC}	V
T _{amb}	Operating ambient temperature range in free air	See DC and AC characteristics	-40 -40		+85 +125	°C
t _r , t _f	Input rise and fall times	$V_{CC} = 1.0V \text{ to } 2.0V$ $V_{CC} = 2.0V \text{ to } 2.7V$ $V_{CC} = 2.7V \text{ to } 3.6V$ $V_{CC} = 3.6V \text{ to } 5.5V$	- - - -	- - - -	500 200 100 50	ns/V

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NOTE:

1. The LV is guaranteed to function down to $V_{CC} = 1.0V$ (input levels GND or V_{CC}); DC characteristics are guaranteed from $V_{CC} = 1.2V$ to $V_{CC} = 5.5V$.

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ABSOLUTE MAXIMUM RATINGS^{1, 2}

In accordance with the Absolute Maximum Rating System (IEC 134). Voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +7.0	V
± I _{IK}	DC input diode current	$V_I < -0.5 \text{ or } V_I > V_{CC} + 0.5 V$	20	mA
± I _{OK}	DC output diode current	$V_{O} < -0.5 \text{ or } V_{O} > V_{CC} + 0.5 V$	50	mA
± I _O	DC output source or sink current – bus driver outputs	-0.5V < V _O < V _{CC} + 0.5V	35	mA
± I _{GND} , ± I _{CC}	DC V _{CC} or GND current for types with – bus driver outputs		70	mA
T _{stg}	Storage temperature range		-65 to +150	°C
P _{TOT}	Power dissipation per package – plastic DIL – plastic mini-pack (SO) – plastic shrink mini-pack (SSOP and TSSOP)	for temperature range: -40 to +125°C above +70°C derate linearly with 12 mW/K above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	750 500 400	mW

NOTES:

DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions, voltages are referenced to GND (ground = 0 V)

					LIMITS			
SYMBOL	PARAMETER	TEST CONDITIONS	-40	°C to +8	5°C	-40°C to	+125°C	UNIT
			MIN	TYP ¹	MAX	MIN	MAX	
		V _{CC} = 1.2 V	0.9			0.9		
\/	HIGH level Input	V _{CC} = 2.0 V	1.4			1.4		V
V_{IH}	voltage	V _{CC} = 2.7 to 3.6 V	2.0			2.0		V
		V _{CC} = 4.5 to 5.5 V	0.7 * V _{CC}			0.7 * V _{CC}		
		V _{CC} = 1.2 V			0.3		0.3	
V	LOW level Input	V _{CC} = 2.0 V			0.6		0.6	$ $ $_{\vee}$ $ $
V_{IL}	voltage	V _{CC} = 2.7 to 3.6 V			0.8		0.8	V
		V _{CC} = 4.5 to 5.5			0.3 * V _{CC}		0.3 * V _{CC}	
		$V_{CC} = 1.2 \text{ V}; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu A$		1.2				
	l <u>-</u>	$V_{CC} = 2.0 \text{ V}; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu A$	1.8	2.0		1.8		
V_{OH}	HIGH level output voltage; all outputs	$V_{CC} = 2.7 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}; -I_O = 100 \mu\text{A}$	2.5	2.7		2.5		V
		$V_{CC} = 3.0 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}; -I_O = 100 \mu\text{A}$	2.8	3.0		2.8		
		$V_{CC} = 4.5 \text{ V}; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 100 \mu A$	4.3	4.5		4.3		
V	HIGH level output voltage; BUS driver	$V_{CC} = 3.0 \text{ V}; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 8\text{mA}$	2.40	2.82		2.20		V
V _{OH}	outputs	$V_{CC} = 4.5 \text{ V}; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 16\text{mA}$	3.60	4.20		3.50		V
		$V_{CC} = 1.2 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu\text{A}$		0				
	l. .	$V_{CC} = 2.0 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu\text{A}$		0	0.2		0.2	
V_{OL}	LOW level output voltage; all outputs	$V_{CC} = 2.7 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu\text{A}$		0	0.2		0.2	V
		$V_{CC} = 3.0 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}; I_O = 100 \mu\text{A}$		0	0.2		0.2	
		V_{CC} = 4.5 V; V_I = V_{IH} or V_{IL} ; I_O = 100 μ A		0	0.2		0.2	
V	LOW level output voltage; BUS driver	$V_{CC} = 3.0 \text{ V}; V_I = V_{IH} \text{ or } V_{IL}; I_O = 8\text{mA}$		0.20	0.40		0.50	V
V_{OL}	outputs	V _{CC} = 4.5 V; V _I = V _{IH} or V _{IL} ; I _O = 16mA		0.35	0.55		0.65	l ^v

Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the
device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to
absolute-maximum-rated conditions for extended periods may affect device reliability.

^{2.} The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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DC ELECTRICAL CHARACTERISTICS (Continued)

Over recommended operating conditions, voltages are referenced to GND (ground = 0 V)

					LIMITS			
SYMBOL	PARAMETER	TEST CONDITIONS	-40	°C to +8	5°C	-40°C to	UNIT	
			MIN	TYP ¹	MAX	MIN	MAX	
I _I	Input leakage current	$V_{CC} = 5.5 \text{ V}; V_I = V_{CC} \text{ or GND}$			1.0		1.0	μА
I _{OZ}	3-State output OFF-state current	$V_{CC} = 5.5 \text{ V}; V_I = V_{IH} \text{ or } V_{IL};$ $V_O = V_{CC} \text{ or GND}$			5		10	μА
I _{CC}	Quiescent supply current; MSI	$V_{CC} = 5.5 \text{ V}; V_{I} = V_{CC} \text{ or GND}; I_{O} = 0$			20.0		160	μА
Δl _{CC}	Additional quiescent supply current per input	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}; V_{I} = V_{CC} - 0.6 \text{ V}$			500		850	μА

NOTE:

AC CHARACTERISTICS

GND = 0V; $t_r = t_f \le 2.5 \text{ns}$; $C_L = 50 \text{pF}$; $R_L = 1 \text{K}\Omega$

			CONDITION			LIMITS											
SYMBOL	PARAMETER	WAVEFORM	CONDITION	_	40 to +85 °	°C	-40 to -	+125 °C	UNIT								
			V _{CC} (V)	MIN	TYP ¹	MAX	MIN	MAX									
			1.2		55												
			2.0		19	24		31									
t _{PHL} /t _{PLH}	Propagation delay nA to nY	Figures 1, 2	2.7		14	18		23	ns								
	10.0011	1 [3.0 to 3.6		10 ²	14		18									
	1 [4.5 to 5.5			12		15										
	3-State output		1.2		75												
			2.0		26	31		39									
t _{PZH} /t _{PZL}	enable time	Figures 2, 3	2.7		19	23		29	ns								
	n OE to nY	1 [3.0 to 3.6		14 ²	18		23									
		1 [4.5 to 5.5			15		19									
			1.2		65												
	3-State output	I –	-	I – –	1 -				1 -		2.0		24	32		39	
t _{PHZ} /t _{PLZ}	disable time	Figures 2, 3	2.7		18	24		29	ns								
	nOE to nY	ga. 55 2, 6	3.0 to 3.6		14 ²	20		24									
			4.5 to 5.5			17		21									

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^{1.} All typical values are measured at $T_{amb} = 25$ °C.

^{1.} Unless otherwise stated, all typical values are measured at $T_{amb} = 25^{\circ}C$ 2. Typical values are measured at $V_{CC} = 3.3 \text{ V}$.

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AC WAVEFORMS

 $V_M = 1.5 \text{ V at } V_{CC} \ge 2.7 \text{ V and } \le 3.6 \text{ V};$

 $V_M = 0.5 \times V_{CC}$ at $V_{CC} < 2.7$ V and ≥ 4.5 V.

VOL and VOH are the typical output voltage drop that occur with the output load.

$$\begin{split} &V_X = V_{OL} + 0.3 \text{ V at } V_{CC} \geq 2.7 \text{ V and} \leq 3.6 \text{ V;} \\ &V_X = V_{OL} + 0.1 \times V_{CC} \text{ at } V_{CC} < 2.7 \text{ V and} \geq 4.5 \text{ V.} \end{split}$$

 $V_Y = V_{OH} - 0.3 \text{ V at } V_{CC} \ge 2.7 \text{ V and } \le 3.6 \text{ V};$ $V_Y = V_{OH} - 0.1 \cdot V_{CC} \text{ at } V_{CC} < 2.7 \text{ V and } \ge 4.5 \text{ V}.$

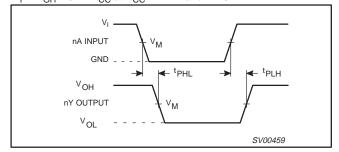


Figure 1. Input (nA) to output (nY) propagation delays and output transition times.

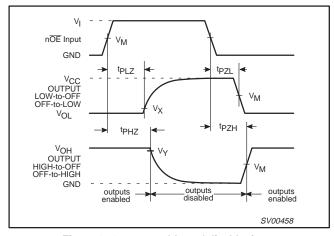


Figure 2. 3-state enable and disable times.

TEST CIRCUIT

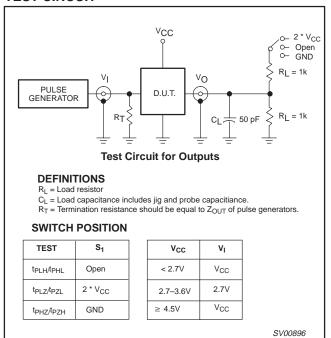


Figure 3. Load circuitry for switching times.

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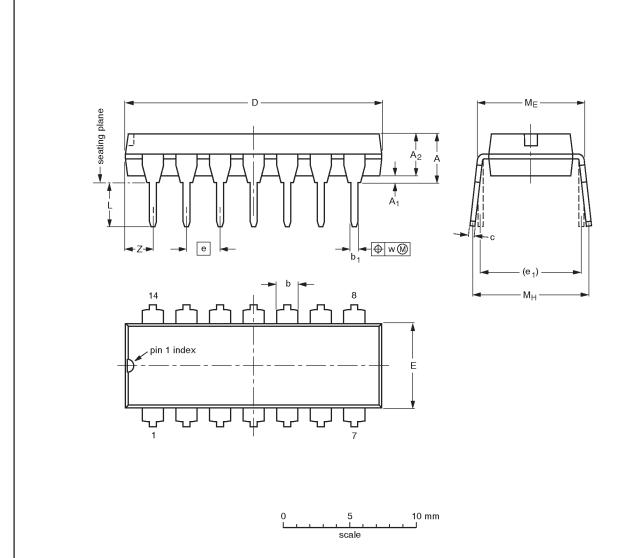
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DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

Note

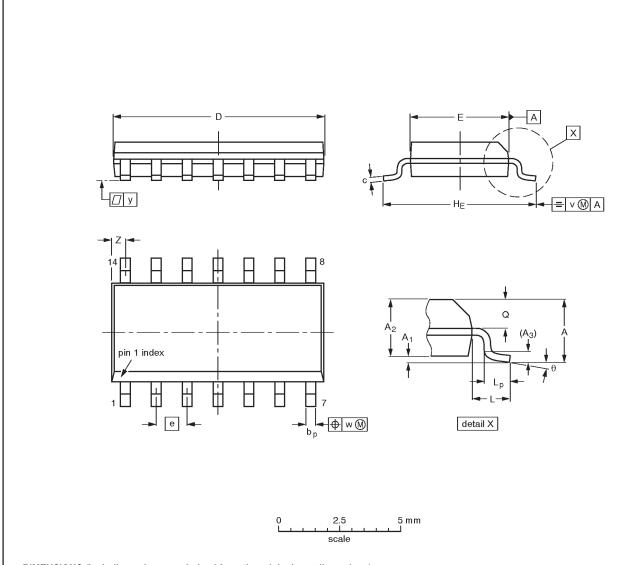
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	
SOT27-1	050G04	MO-001AA			92-11-17 95-03-11	

74LV125

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	Α1	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Ø	v	w	у	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.0098 0.0039	0.057 0.049	0.01		0.0098 0.0075	0.35 0.34	0.16 0.15	0.050	0.24 0.23	0.041	0.039 0.016		0.01	0.01	0.004	0.028 0.012	0°

Note

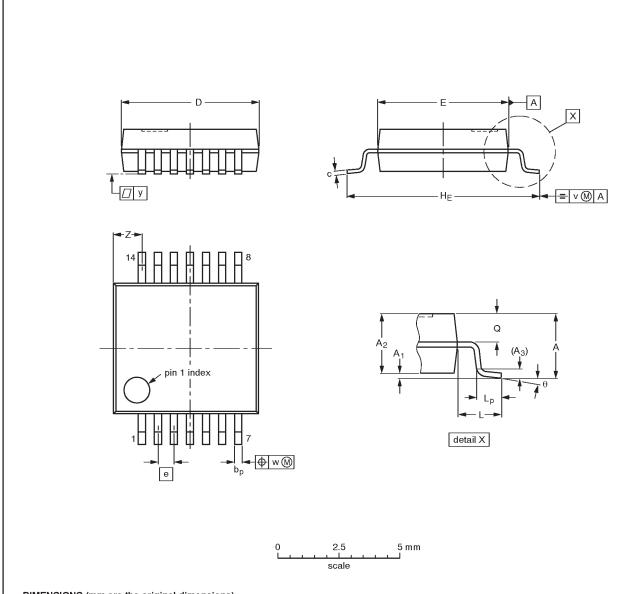
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT108-1	076E06\$	MS-012AB				91-08-13 95-01-23

74LV125

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	рb	c	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	٧	w	у	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8° 0°

Note

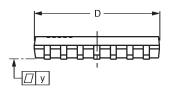
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

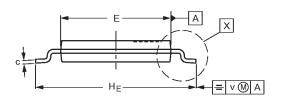
OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	PROJECTION	1330E DATE		
SOT337-1		MO-150AB				95-02-04 96-01-18

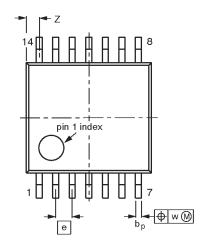
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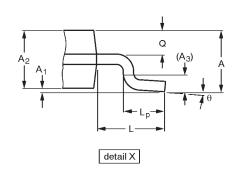
TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

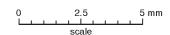
SOT402-1











DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	A ₃	bр	c	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT402-1		MO-153				94-07-12 95-04-04

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NOTES

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	DEFINITIONS						
Data Sheet Identification	Product Status	Definition					
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.					
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.					
Product Specification	Full Production	This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.					

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